

## INVERTED LEAD FRAME ON SUBSTRATE

### ABSTRACT

A semiconductor package, and method of making a semiconductor package, with a plurality of dies, wherein one die is attached to an inverted lead frame and another die is attached to a substrate. The leadframe is then attached to the substrate. More specifically, the semiconductor package includes a substrate, a lead frame and a plurality of leads. The lead frame is attached to the top surface of the substrate. The bottom surface of a first die is attached to the top surface of the substrate and the first die is electrically connected to the substrate. The top surface of a second die is attached to the bottom die pad surface of the lead frame and the second die is electrically connected to the leadframe. An encapsulant covers at least a portion of the lead frame and substrate.

**Fig. 1A**